• STS High Rate HRM\textsuperscript{ASE} (Advanced Silicon Etching) system is located in the Class-1000 cleanroom.

• It is designed to etch deep silicon structures with aspect ratios exceeding 50:1, photoresist selectivity ratios exceeding 100:1, and etch depth uniformity better than \( \pm 3\% \) anisotropic.

• The ASE process achieves anisotropic etching of silicon through a series of alternating passivation and etch steps based on the “Bosch Process”.